

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	10	US-5446309-\$.DID. OR US-6274937-\$.DID. OR US-6529093-\$.DID. OR US-6531668-\$.DID. OR US-6573822-\$.DID. OR US-6822535-\$.DID. OR US-6850133-\$.DID. OR US-6880235-\$.DID. OR US-6933808-\$.DID. OR US-6972650-\$.DID.	USPAT	OR	OFF	2007/01/18 13:58
S2	2	("20030045044").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/18 13:58
S5	2	("20050030128").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/18 13:59
S6	2	("20050122001").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/18 13:59
S7	2	("20050140468").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/18 13:59
S8	18	S1 S2 S5 S6 S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/18 14:09

## EAST Search History

S9	173	((silicon or si) near3 (board or support or substrate or wafer)) and (mems near5 (microfluidic)) and (optical or led or light)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 14:36
S10	8189	((silicon or si) near3 (substrate)) and (mems) and (optical or led or light)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 11:32
S11	222	((silicon or si) near3 (substrate)) and (mems with (microfluidic)) and (optical or led or light)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 14:38
S12	75	S11 not S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 15:25
S13	72	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and (((silicon or si) adj substrate) with resistive) and (optical and sensor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 16:56
S14	59	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and (((silicon or si) adj substrate) with pdms)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:04
S15	14	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and (((silicon or si) adj substrate) with resistive) and (optical and sensor) and (bonding adj pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:47

## EAST Search History

S16	659	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and ((silicon or si) adj substrate) and (optical and sensor) and (bonding adj pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 17:00
S17	216	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and ((silicon or si) adj substrate) and (optical and sensor) and (bonding adj pad) and MEMS	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 18:17
S18	41	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and ((silicon or si) adj substrate) and (microfluidic) and (bonding adj pad) and MEMS	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 19:29
S19	41	((silicon or si) adj substrate) and (microfluidic) and (bonding adj pad) and MEMS	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:05
S20	410	S18 not6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 18:45
S21	0	S18 not S19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/18 18:45
S22	7003	((silicon or si) near3 (substrate)) near3 integrated	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 14:52

## EAST Search History

S23	376	S22 and (mems) and (optical or led or light)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 12:39
S24	1	("20050104176").PN.	US-PGPUB; USPAT	OR	OFF	2007/01/19 11:42
S25	390	S22 and (bonding adj pads)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 12:38
S26	24	S25 and (hermetically or hermetic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:10
S27	90	((silicon or si) near3 (carrier)) near3 integrated	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 12:39
S28	7	S27 and (bonding adj pads)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 12:39
S29	295	((silicon or si) near3 (carrier)) and (bonding adj pads)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:08
S30	20	S29 and (mems) and (optical or led or light)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 12:40

## EAST Search History

S31	98	((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) with (embedded or processed))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:09
S32	2628	((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 07:06
S33	161	S32 and (bonding adj pads)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 17:16
S34	4827	((silicon or si) near3 (substrate or carrier or wafer)) same (MEMS)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 17:28
S35	271	S34 and (bonding adj pads)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 17:16
S36	110	S35 not S33	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 17:16
S37	7659	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and ((cap or lid) with (si or silicon)) and ((si or silicon) near3 (substrate or carrier or wafer))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 17:30

## EAST Search History

S38	419	S37 and (bonding adj pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 18:55
S39	7144	laser same (silicon adj substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 18:55
S40	3209	laser with (silicon adj substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 18:56
S41	574	"257"/\$6.ccls. and (laser with (silicon adj substrate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 18:56
S42	231	(semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and ((silicon or si) adj substrate) and ((lid or cap) with (via)) and (bonding adj pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/19 19:32
S43	978	((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) and (microfluidic or (micro adj fluidic) or (fluid))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 08:57
S44	794	S43 and (@rlad<="20040331" @ad<="20040331" @pd<="20040331")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:48
S45	1	("7125451").PN.	USPAT	OR	OFF	2007/07/09 07:14
S46	1	("7128783").PN.	USPAT	OR	OFF	2007/07/09 07:14

## EAST Search History

S47	1	("20050063431").PN.	US-PGPUB	OR	OFF	2007/07/09 07:58
S48	0	((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) and (bonding adj pad) and (trace or interconnection or interconnect)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 08:58
S49	140	((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) and (bonding adj pad) and (trace or interconnection or interconnect)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:01
S50	124	S49 and (@rlad<="20040331" @ad<="20040331" @pd<="20040331")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 09:07
S51	62	S50 not S44	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 08:58
S52	185	((silicon or si) near3 (substrate or carrier or wafer)) with (sensor) and (bonding adj pad) and (trace or interconnection or interconnect)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:03
S53	164	S52 and (@rlad<="20040331" @ad<="20040331" @pd<="20040331")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 09:43
S54	856	S51 S44	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 09:07

## EAST Search History

S55	148	S53 not S54	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 09:07
S56	205	((silicon or si) near3 (substrate or carrier or wafer)) with (lasor or optical) and (bonding adj pad) and (trace or interconnection or interconnect)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:03
S57	1004	S54 S55	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 09:43
S58	177	S56 not S57	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 09:43
S59	168	S58 and (@rlad<="20040331" @ad<="20040331" @pd<="20040331")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/09 09:43
S60	5	((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) and (bonding adj pad) and (trace or interconnection or interconnect)) and @pd>="20070709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:01
S61	5	((silicon or si) near3 (substrate or carrier or wafer)) with (sensor) and (bonding adj pad) and (trace or interconnection or interconnect)) and @pd>="20070709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:03



## EAST Search History

S62	1	(((silicon or si) near3 (substrate or carrier or wafer)) with (lasor or optical) and (bonding adj pad) and (trace or interconnection or interconnect)) and @pd>="20070709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:03
S63	19	((semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and (((silicon or si) adj substrate) with pdms)) and @pd>="20070118"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:05
S64	5	(((silicon or si) adj substrate) and (microfluidic) and (bonding adj pad) and MEMS) and @pd>="20070118"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:05
S65	33	S60 S61 S62 S63 S64	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:09
S66	5	(((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) with (embedded or processed))) and @pd>="20070118"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/21 18:09
S67	5	(((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) and (bonding adj pad) and (trace or interconnection or interconnect)) and @pd>="20070709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:01
S68	5	(((silicon or si) near3 (substrate or carrier or wafer)) with (sensor) and (bonding adj pad) and (trace or interconnection or interconnect)) and @pd>="20070709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:01

## EAST Search History

S69	1	(((silicon or si) near3 (substrate or carrier or wafer)) with (lasor or optical) and (bonding adj pad) and (trace or interconnection or interconnect)) and @pd>="20070709"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:01
S70	19	((semiconductor or ic or die or chip or (integrated adj circuit) or (electronic adj device)) and (((silicon or si) adj substrate) with pdms)) and @pd>="20070118"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:01
S71	5	(((silicon or si) adj substrate) and (microfluidic) and (bonding adj pad) and MEMS) and @pd>="20070118"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:01
S72	33	S67 S68 S69 S70 S71	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:01
S73	5	(((silicon or si) near3 (substrate or carrier or wafer)) with (MEMS) with (embedded or processed))) and @pd>="20070118"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:01
S74	38	S72 S73	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:43
S75	1067	257/414.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:43

## EAST Search History

S76	1030	257/415.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:44
S77	638	257/499.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:44
S78	2618	S75 S76 S77	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:44
S79	513	S78 and (mems or (micro adj electro adj mechanical))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:47
S80	388	S79 and (@rlad<="20040331" @ad<="20040331" @pd<="20040331")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/22 15:48